April 2011

Science-Technology Division

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Hello from Denver, Colorado.

I am really looking forward to the SLA Annual Conference this year. Philadelphia is a fantastic city, and I hope that the conference will be just as good. The Sci-Tech Division has a good slate of sessions, and we are collaborating with a number of other SLA Divisions to provide many of our sessions.

Over the next month, we will provide more details concerning these sessions on the new Sci-Tech Division website (http://scitech.sla.org) and on the discussion list. The blog posts will automatically go out on our Twitter feed, so please follow the postings at http://twitter.com/sla_dst.

If you are a new member of the Division, or if this is your first trip to the SLA Annual Conference, we would like to have you attend the Newcomer’s Lunch on Sunday, June 12th from 11:30 a.m. till 1:00 p.m. The location will be announced on the discussion list and the website. If you are a Division leader, we would like to have you attend the business meeting from 1:30 to 3:00 p.m. that Sunday.

On Monday, June 13th, the Business Meeting and Breakfast will be that morning. We will also have our first topical session on forensic investigation. Some officers from the Philadelphia Office of the Federal Bureau of Investigation (FBI) will explain how they conduct investigations at the “Crime Scene Investigation: Philadelphia” session. That afternoon, we co-sponsor a session on “Collaborations Across Disciplines.” Learn about efforts to help researchers collaborate across disciplines. Speakers include representatives from FriendFeed, Mendeley, Collexis, VIVO and BibApp. We are also sponsoring a session on “Visualizing Science.” See what’s happening in the world of data visualization, including new and easy to use applications.


On Tuesday, June 14th, we co-sponsor the “Developments in Informatics” session. Come hear the latest developments in informatics in the fields of chemistry, biological sciences, and physics and astronomy. The “Science of Ice Cream” session will feature a researcher from the Pennsylvania State University Creamery (http://www.creamery.psu.edu). Later that evening, we co-sponsor the “All Sciences Poster Session and Reception.” I know that there are going to be some really interesting poster presentations.

On Wednesday, June 15th, the Division will sponsor or co-sponsor four more great sessions. For a light breakfast, please stop by the “Science 2.1” session for a discussion on how scientific communication methods are iteratively changing. The ever popular James Manasco and Mary Frances Lembo will present at another “Sci-Tech 101” session. This year, they will discuss materials science and marine science resources.

Also on Wednesday the 15th, we co-sponsor the “Computer Science Roundtable,” and we have a great slate of papers that will be presented at the “Data: The Next Generation” session. Peer-reviewed contributed papers will be presented on the topic of data curation. The four papers are: “ChemSpider: Hosting, Linking and Curating Chemistry Data for the Community” by Valery Tkachenko, CTO ChemSpider; “Starting from Scratch: Assessing the Library’s Role in Data Management on Campus” by Christie Peters, Robin Dasler, and Anita Riley from the University of Houston; “Planning for Data Curation in the Small Liberal Arts College Environment” by Sarah Goldstein and Sarah Oelker, Mount Holyoke College; and “Data Management Plan Advising? A New Business Venture for Libraries” by Andrew Sallans, University of Virginia. Please go to http://scitech.sla.org/2011/03/data-the-next-generation-session-information/ for more information. Please note that some snacks and
beverages will be provided to help keep you attentive at the session.

By all means, stay in Philadelphia on Thursday, June 16th as well! We are co-sponsoring a Tastykake Factory Tour at the Old Naval Shipyard, and we have two unofficial tours. Several Sci-Tech members are able to visit the Franklin Institute, and we may have space for people to tour the EPA Library. Please see http://epatour2011.pbworks.com for more information. Please email me (joseph.kraus@du.edu) if you would like to sign up.

It has been a delight to work on planning the programs for this year’s Sci-Tech Division sessions. I hope you will enjoy the trip out to Philadelphia; I know I will.

Joe Kraus
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Sci-Tech Division Vendor Sponsors for 2011

Carol Lucke, Vendor Relations Chair, Sci-Tech Division

The Sci-Tech Division would like to recognize our generous sponsor vendors for their financial assistance and support for the 2011 SLA Conference. Without them the Sci-Tech Division would not be able to offer the relevant, educational and interesting programs and networking opportunities our members count on and expect. This year our vendor supporters include, in alphabetical order:

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Annual Reviews
ASTM
CAS
Elsevier
HW Wilson
IEEE
Inspec
Knovel
SPIE
Thomson Reuters
World Scientific

Please be sure to visit our sponsors at the Exhibitors Center and thank them for their support!
### Science-Technology Division New Members

*Submitted by Sarah Oelker, Membership Committee Chair, Science-Technology Division*

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<th>Name</th>
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<tr>
<td>Teresa Wilkins</td>
<td>Secaucus, NJ</td>
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<td>Jason Youngstrom</td>
<td>Golden, CO</td>
<td>USA</td>
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<td>Pamela Cheek</td>
<td>Asheville, NC</td>
<td>USA</td>
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<td>Lesley Skalla</td>
<td>Durham, NC</td>
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<td>Geeta Khulbe</td>
<td>Delhi, NCT</td>
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<td>Yousef Al Araj</td>
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<td>Yasair Al-Faiyz</td>
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<td>Leslie Bitman</td>
<td>Waltham, MA</td>
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<td>Sushma Gupta</td>
<td>Roorkee, Uttarakhand</td>
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<td>Charles Phelps</td>
<td>Regina, SK</td>
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<td>Danielle Pollock</td>
<td>Albuquerque, NM</td>
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<td>Chitra S</td>
<td>Poojapura, Kerala</td>
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<td>Christopher Turner</td>
<td>Syracuse, NY</td>
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<tr>
<td>Emily Weak</td>
<td>San Francisco, CA</td>
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ENCYCLOPEDIA OF THERMAL PACKAGING

Set 1: Thermal Packaging Techniques (A 4-Volume Set)
Set 2: Thermal Packaging Applications (A 4-Volume Set)

Successful thermal packaging is the key differentiator in electronic products, as diverse as supercomputers and cell phones, and continues to be of pivotal importance in the refinement of traditional products and in the development of products for new applications. The Encyclopedia of Thermal Packaging, compiled into four multi-volume sets (Set 1: Thermal Packaging Techniques, Set 2: Thermal Packaging Applications, Set 3: Thermal Packaging Tools, Set 4: Thermal Packaging Configurations), will provide a comprehensive, one-stop treatment of the techniques, applications, tools, and configurations of electronic thermal packaging.

Each volume in this set is comprised of 250–350 pages and is written by world experts in the specific aspect of thermal management of electronics.

Readership: Undergraduate and graduate students studying mechanical, electrical and electronic engineering; packaging engineers, electronic product development engineers, and product managers, as well as to researchers in thermal management of electronic and photonic components and systems.

The books included in “Set 1: Thermal Packaging Techniques” focus on the technology “building blocks” used to assemble a complete thermal management system and provide detailed descriptions of the underlying phenomena, modeling equations, and correlations, as well as guidance for achieving the optimal designs of individual “building blocks” and their insertion in the overall thermal solution. Specific volumes deal with coldplates, microchannel coolers, heat sinks, thermal interface materials (TIMs), thermoelectric microcoolers, and immersion cooling modules.

The books included in “Set 2: Thermal Packaging Applications” focus on the unique considerations which guide the design and operation of electronic systems in various distinct applications and address the thermal management requirements, operating environments, and best available thermal solutions for these applications. Volumes offered in Set 2 of the Thermal Packaging Encyclopedia will deal with solid state lighting, data centers, power electronics, photovoltaic arrays, and experimental measurement techniques.
Science-Technology Division Call for Candidates
Submitted by Pam Enrici, Nominating Committee Chair, Science-Technology Division

It’s that time of year and the Sci-Tech Division is looking for a few good people – well, we’re always on the lookout for lots of good people. But these volunteers will be filling two major jobs within the Division – Chair-Elect and Secretary.

The Chair-Elect is really a three year commitment – the first year, the Chair-Elect will work on planning the next year’s Divisions activities at the Annual Conference and start really learning the ropes. The next year, he/she will serve as Chair, and the final year, they will work with the governing documents of the Division as Past Chair. Anyone who has served as Chair knows the amount of work and dedication that it takes to keep things moving forward throughout your term, but at the same time it is an extremely rewarding activity. You’ll meet new people both in the Division and throughout the wider SLA, you’ll learn how to do lots of new things, and I feel, have a good time and equally important, feel good about helping. There is some financial help from the Division for travel, as well.

The Secretary position is a two year term. You will need to take minutes at the Business Meeting and the Board Meeting at the Annual Conference as well as take minutes for board meetings that take place at other times.

I realize that not everyone is in a position where they can dedicate this much time and energy to the Sci-Tech Division, but if you are, please volunteer (or we’ll come looking!). Remember, the Sci-Tech Division is only as good as the people who help.

For more details and/or to volunteer for either position, please contact Pam Enrici (Past-Past Chair of Sci-Tech Division and Chair of the Nominating Committee). I can be reached at 218-726-8586 or you can e-mail me at penrici@d.umn.edu. Feel free to contact others on the committee: Christine Whitaker (Christine. Whitaker@uscmed.sc.edu), Anna Ren (annawu@northwestern.edu), Debal Kar (dckar@teri.res.in), and Nancy Wilmes (n.wilmes@wayne.edu) or talk to our current Chair, Joe Kraus (joseph.kraus@du.edu).